



SiGe BiCMOS INTEGRATED CIRCUIT

μ PD5740T6N

LOW NOISE WIDEBAND AMPLIFIER IC WITH THROUGH FUNCTION

DESCRIPTION

The μ PD5740T6N is a low noise wideband amplifier IC mainly designed for the portable digital TV application. This IC has achieved low noise figure and the wideband operation. The μ PD5740T6N has an LNA pass-through function (bypass function) to prevent the degradation of the received signal quality at the strong electric field, and achieve the high reception sensitivity and low power consumption.

The package is a 6-pin plastic TSON (Thin Small Out-line Non-leaded) (T6N) suitable for surface mount.

This IC is manufactured using our latest SiGe BiCMOS process that shows superior high frequency characteristics.

FEATURES

- Low voltage operation : $V_{CC} = 2.3$ to 3.3 V (2.8 V TYP.)
- Low mode control voltage : $V_{cont(H)} = 1.0$ V to V_{CC} , $V_{cont(L)} = 0$ to 0.5 V
- Low current consumption : $I_{CC1} = 5.0$ mA TYP. @ $V_{CC} = 2.8$ V (LNA-mode)
: $I_{CC2} = 1$ μ A MAX. @ $V_{CC} = 2.8$ V (Bypass-mode)
- Low noise (LNA-mode) : $NF1 = 1.5$ dB TYP. @ $V_{CC} = 2.8$ V, $f = 470$ MHz
: $NF2 = 1.5$ dB TYP. @ $V_{CC} = 2.8$ V, $f = 770$ MHz
- High gain (LNA-mode) : $GP1 = 15.0$ dB TYP. @ $V_{CC} = 2.8$ V, $f = 470$ MHz
: $GP2 = 13.5$ dB TYP. @ $V_{CC} = 2.8$ V, $f = 770$ MHz
- Low insertion loss (Bypass-mode) : $L_{ins1} = 1.1$ dB TYP. @ $V_{CC} = 2.8$ V, $f = 470$ MHz
: $L_{ins2} = 1.3$ dB TYP. @ $V_{CC} = 2.8$ V, $f = 770$ MHz
- High-density surface mounting : 6-pin plastic TSON (T6N) package ($1.5 \times 1.5 \times 0.37$ mm)
- Included protection circuits for ESD

APPLICATION

- Low noise amplifier for the portable and mobile digital TV system, etc.

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μ PD5740T6N-E2	μ PD5740T6N-E2-A	6-pin plastic TSON (T6N) (Pb-Free)	C3U	<ul style="list-style-type: none">• 8 mm wide embossed taping• Pin 1, 6 face the perforation side of the tape• Qty 3 kpcs/reel

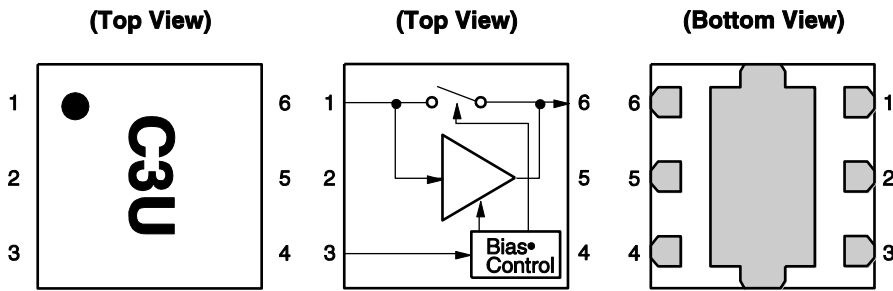
Remark To order evaluation samples, please contact your nearby sales office.

Part number for sample order: μ PD5740T6N-A

Caution: Observe precautions when handling because these devices are sensitive to electrostatic discharge

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	INPUT
2	GND
3	V _{cont}
4	V _{cc}
5	NC
6	OUTPUT

Remark Exposed pad : GND

TRUTH TABLE

V _{cont}	Gain	Mode
H	High	LNA-mode
L	Low	Bypass-mode

Remark "H" = V_{cont} (H), "L" = V_{cont} (L)

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Test Conditions	Ratings	Unit
Supply Voltage	V _{cc}	T _A = +25°C	3.6	V
Mode Control Voltage	V _{cont}	T _A = +25°C	3.6	V
Total Power Dissipation	P _{tot}		150	mW
Operating Ambient Temperature	T _A		-40 to +85	°C
Storage Temperature	T _{stg}		-55 to +150	°C
Input Power	P _{in}		+33	dBm

RECOMMENDED OPERATING RANGE

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{cc}	2.3	2.8	3.3	V
Mode Control Voltage (H)	V _{cont} (H)	1.0	-	V _{cc}	V
Mode Control Voltage (L)	V _{cont} (L)	0	-	0.5	V
Operating Frequency	f	50	-	1 800	MHz
Operating Ambient Temperature	T _A	-40	+25	+85	°C
Input Power (LNA-mode)	P _{in}	-	-	+7	dBm
Input Power (Bypass-mode)	P _{in}	-	-	+15	dBm

ELECTRICAL CHARACTERISTICS 1 (DC Characteristics)

(T_A = +25°C, V_{CC} = 2.8 V, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current 1	I _{cc1}	V _{cont} = 2.8 V, No Signal (LNA-mode)	3.8	5.0	6.5	mA
Circuit Current 2	I _{cc2}	V _{cont} = 0 V, No Signal (Bypass-mode)	–	–	1	μA
Mode Control Current 1	I _{cont1}	V _{cont} = 2.8 V, No Signal (LNA-mode)	–	40	100	μA
Mode Control Current 2	I _{cont2}	V _{cont} = 0 V, No Signal (Bypass-mode)	–	–	1	μA

ELECTRICAL CHARACTERISTICS 2 (LNA-mode)

(T_A = +25°C, V_{CC} = V_{cont} = 2.8 V, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Power Gain 1	G _{P1}	f = 470 MHz, P _{in} = –30 dBm	13.0	15.0	17.0	dB
Power Gain 2	G _{P2}	f = 770 MHz, P _{in} = –30 dBm	11.5	13.5	15.5	dB
Noise Figure 1	NF1	f = 470 MHz, excluded PCB and connector losses Note	–	1.5	2.0	dB
Noise Figure 2	NF2	f = 770 MHz, excluded PCB and connector losses Note	–	1.5	2.0	dB
Input Return Loss 1	RL _{in1}	f = 470 MHz, P _{in} = –30 dBm	7	12	–	dB
Input Return Loss 2	RL _{in2}	f = 770 MHz, P _{in} = –30 dBm	7	10	–	dB
Output Return Loss 1	RL _{out1}	f = 470 MHz, P _{in} = –30 dBm	7	14	–	dB
Output Return Loss 2	RL _{out1}	f = 770 MHz, P _{in} = –30 dBm	7	11	–	dB
Input 3rd Order Intercept Point 1	IIP ₃₁	f ₁ = 470 MHz, f ₂ = 471 MHz, P _{in} = –30 dBm	–4.0	–1.0	–	dBm
Input 3rd Order Intercept Point 2	IIP ₃₂	f ₁ = 770 MHz, f ₂ = 771 MHz, P _{in} = –30 dBm	–1.0	+2.0	–	dBm

Note Input PCB and connector losses: 0.05 dB (at 470 MHz), 0.08 dB (at 770 MHz)

ELECTRICAL CHARACTERISTICS 3 (Bypass-mode)
(T_A = +25°C, V_{CC} = 2.8 V, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	L _{ins1}	f = 470 MHz, P _{in} = -10 dBm, excluded PCB and connector losses Note	-	1.1	2	dB
Insertion Loss 2	L _{ins2}	f = 770 MHz, P _{in} = -10 dBm, excluded PCB and connector losses Note	-	1.3	2	dB
Input Return Loss 1	RL _{in1}	f = 470 MHz, P _{in} = -10 dBm	10	20	-	dB
Input Return Loss 2	RL _{in2}	f = 770 MHz, P _{in} = -10 dBm	10	17	-	dB
Output Return Loss 1	RL _{out1}	f = 470 MHz, P _{in} = -10 dBm	10	20	-	dB
Output Return Loss 2	RL _{out1}	f = 770 MHz, P _{in} = -10 dBm	10	17	-	dB
Input 3rd Order Intercept Point	IIP ₃	f1 = 770 MHz, f2 = 771 MHz, P _{in} = -2.5 dBm	+20	+30	-	dBm

Note Input-output PCB and connector losses: 0.10 dB (at 470 MHz), 0.16 dB (at 770 MHz)

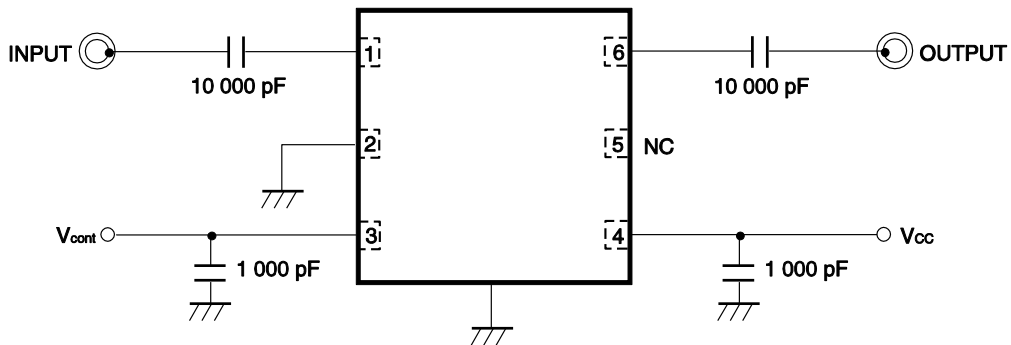
STANDARD CHARACTERISTICS FOR REFERENCE 1 (LNA-mode)
 (T_A = +25°C, V_{CC} = V_{cont} = 2.8 V, unless otherwise specified)

Parameter	Symbol	Test Conditions	Reference	Unit
Isolation 1	ISL1	f = 470 MHz, P _{in} = -30 dBm	20	dB
Isolation 2	ISL2	f = 770 MHz, P _{in} = -30 dBm	20	dB
Gain 1 dB Compression Output Power 1	P _{O(1 dB) 1}	f = 470 MHz	-5.5	dBm
Gain 1 dB Compression Output Power 2	P _{O(1 dB) 2}	f = 770 MHz	-5.0	dBm

STANDARD CHARACTERISTICS FOR REFERENCE 2 (Bypass-mode)
 (T_A = +25°C, V_{CC} = 2.8 V, V_{cont} = 0 V, unless otherwise specified)

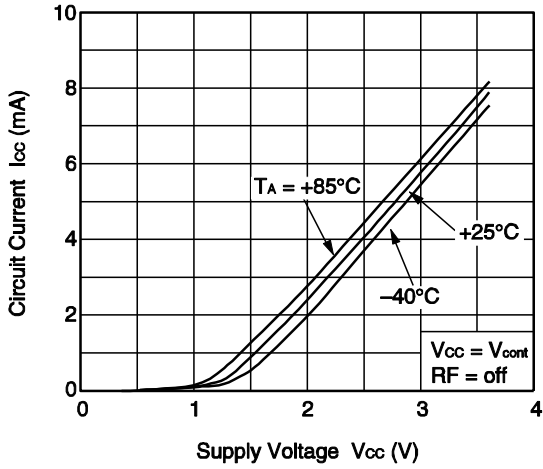
Parameter	Symbol	Test Conditions	Reference	Unit
Gain 1 dB Compression Output Power	P _{O(1 dB)}	f = 770 MHz	+8	dBm

TEST CIRCUIT

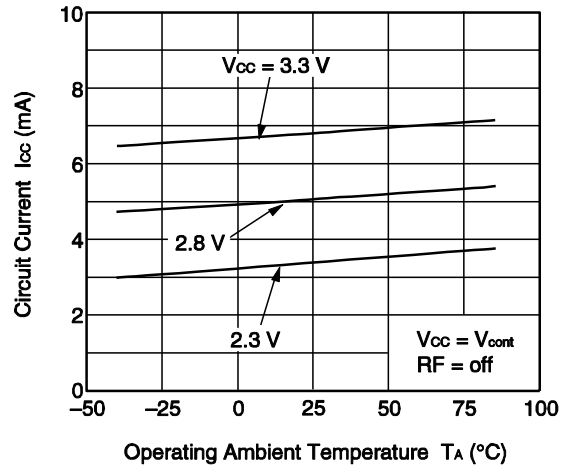


TYPICAL CHARACTERISTICS 1 (DC Characteristics) ($T_A = +25^\circ\text{C}$, unless otherwise specified)

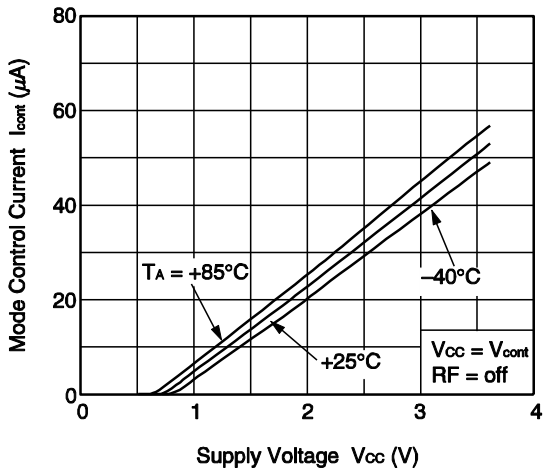
CIRCUIT CURRENT vs. SUPPLY VOLTAGE



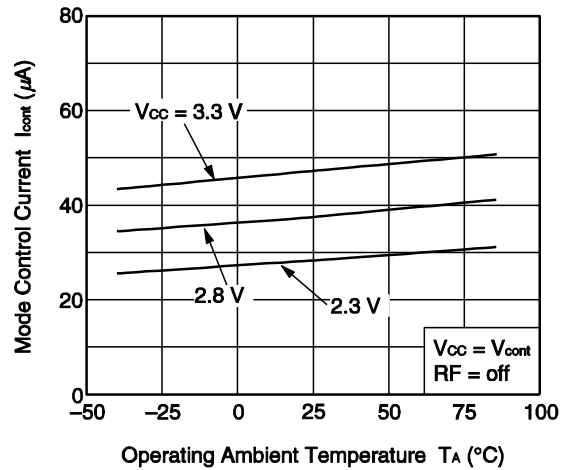
CIRCUIT CURRENT vs. OPERATING AMBIENT TEMPERATURE



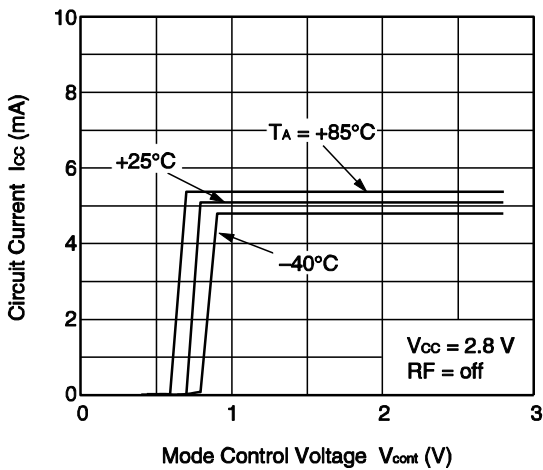
MODE CONTROL CURRENT vs. SUPPLY VOLTAGE



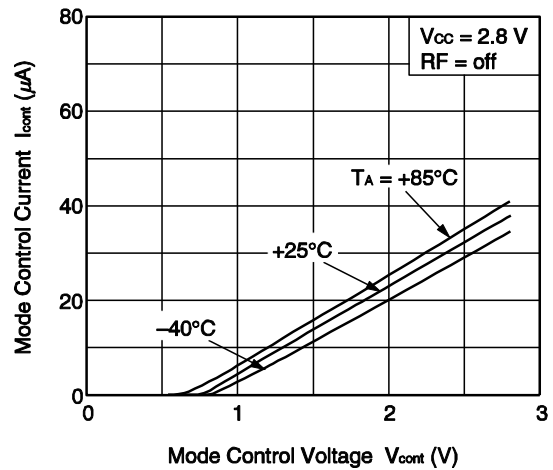
MODE CONTROL CURRENT vs. OPERATING AMBIENT TEMPERATURE



CIRCUIT CURRENT vs. MODE CONTROL VOLTAGE

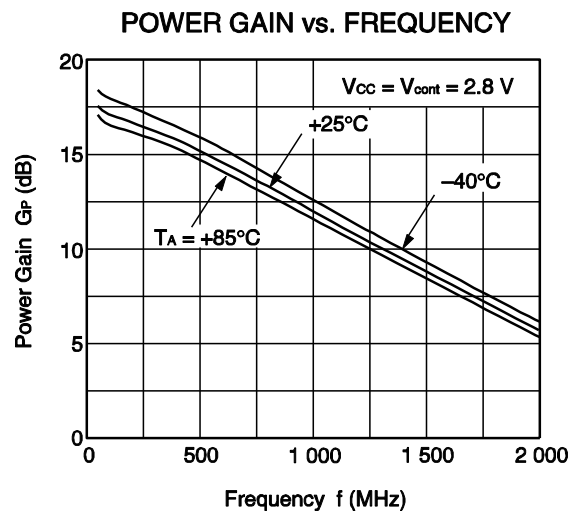
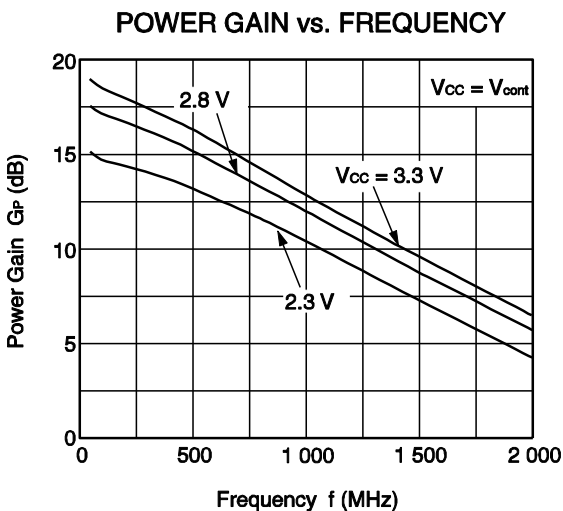
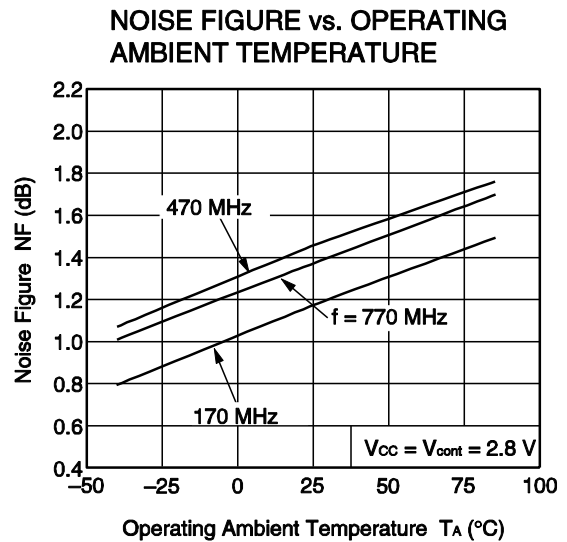
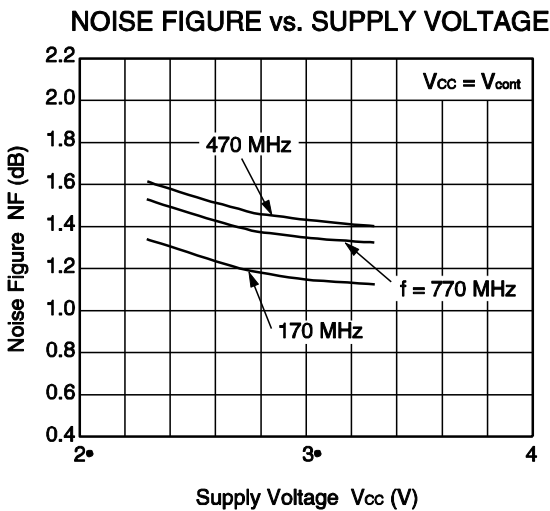
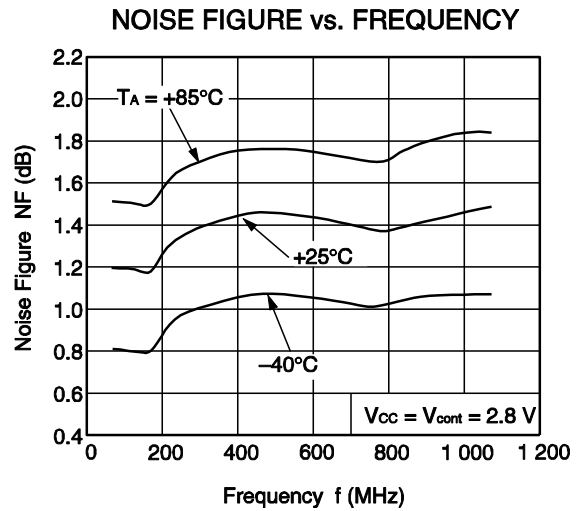
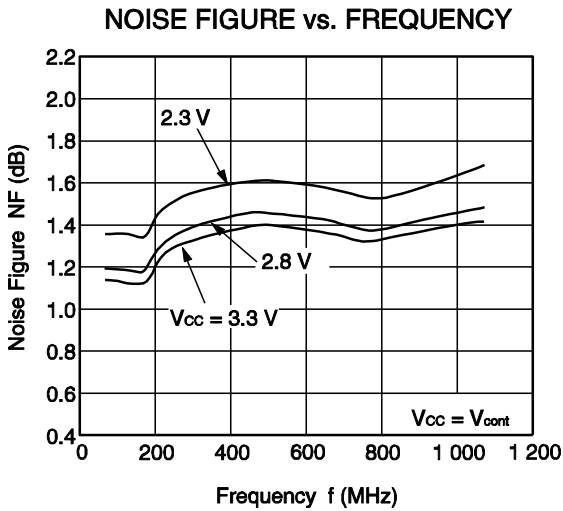


MODE CONTROL CURRENT vs. MODE CONTROL VOLTAGE



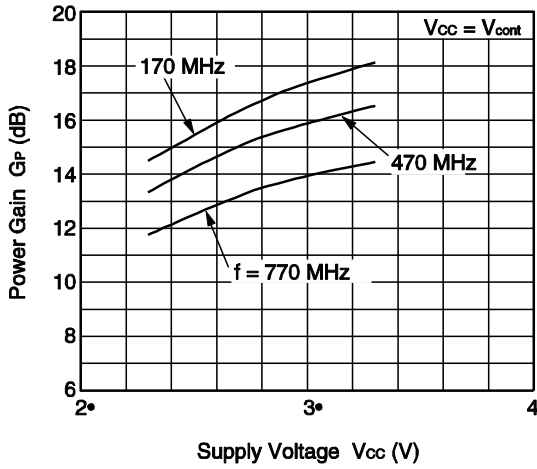
Remark The graphs indicate nominal characteristics.

TYPICAL CHARACTERISTICS 2 (LNA-mode) ($T_A = +25^\circ\text{C}$, unless otherwise specified)

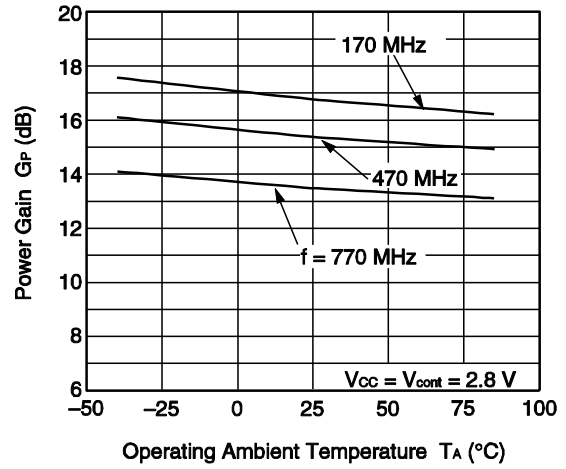


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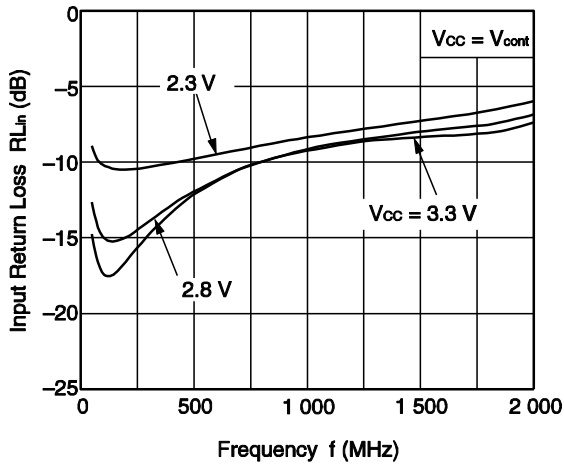
POWER GAIN vs. SUPPLY VOLTAGE



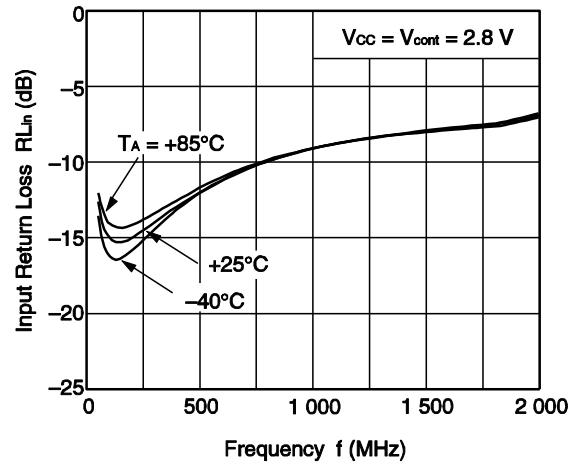
POWER GAIN vs. OPERATING AMBIENT TEMPERATURE



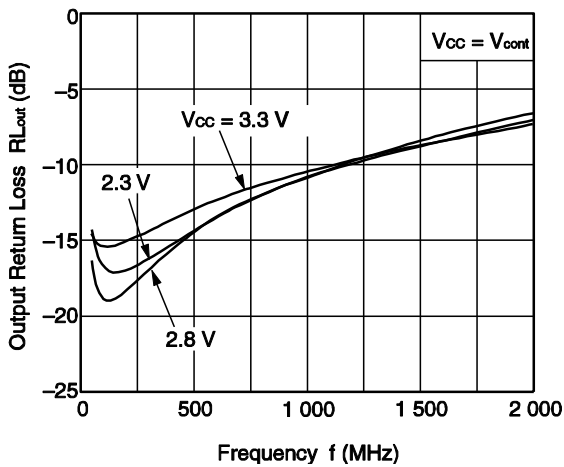
INPUT RETURN LOSS vs. FREQUENCY



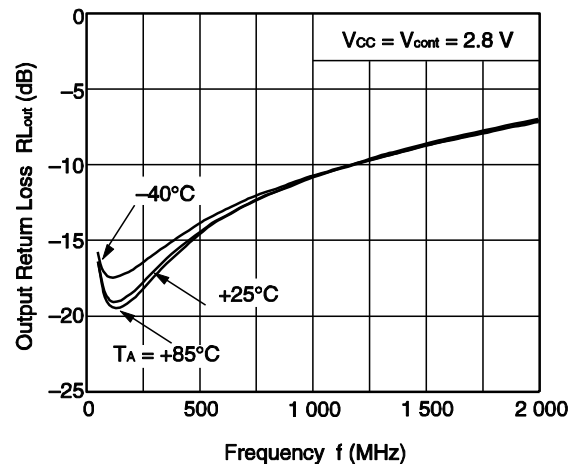
INPUT RETURN LOSS vs. FREQUENCY



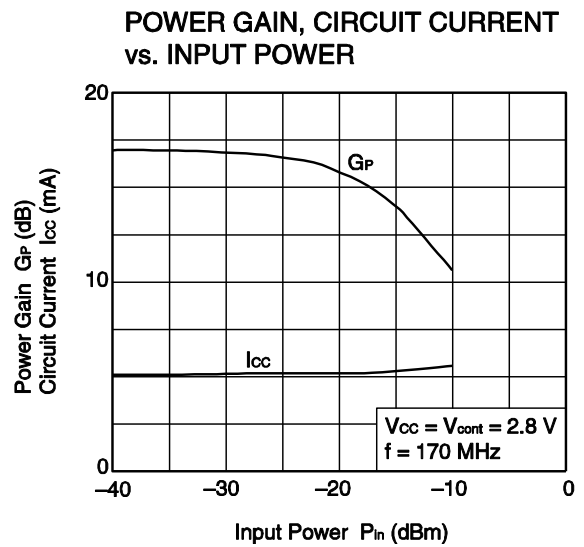
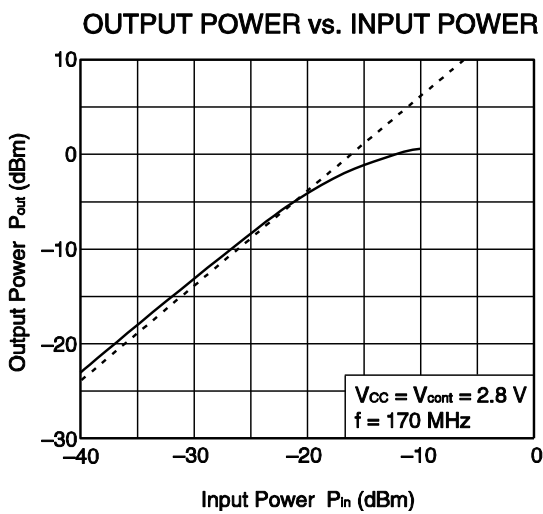
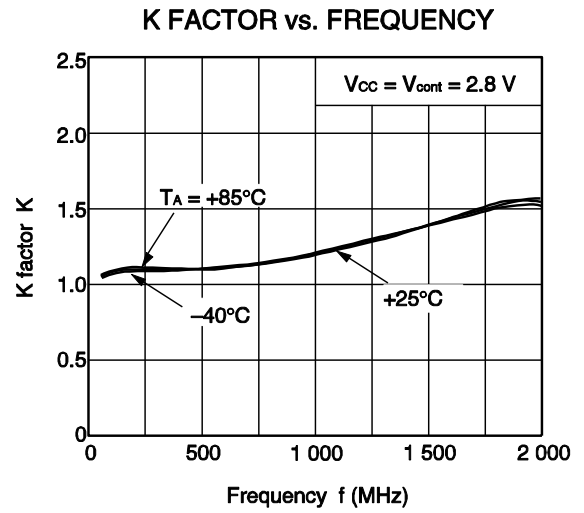
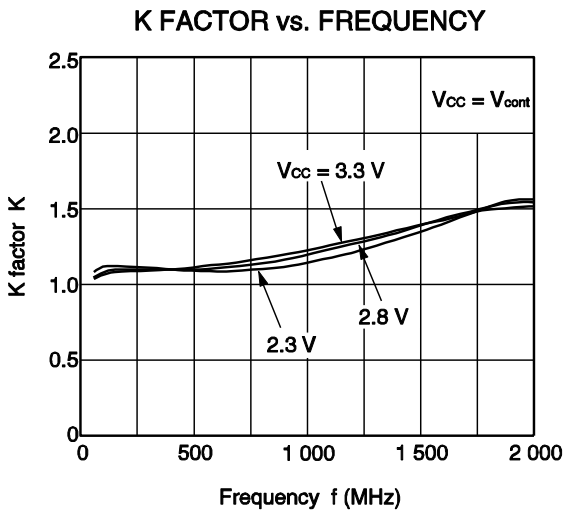
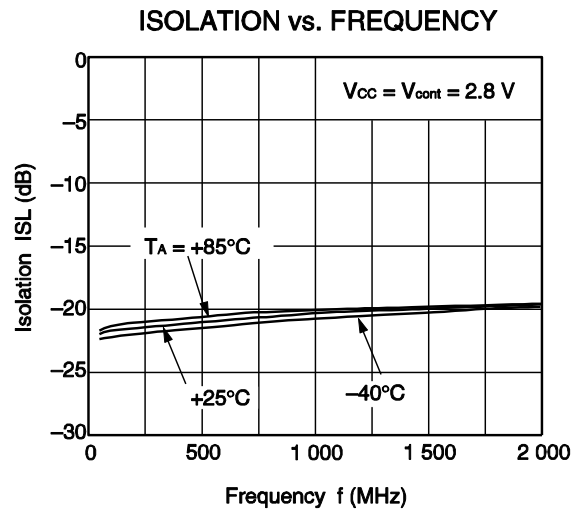
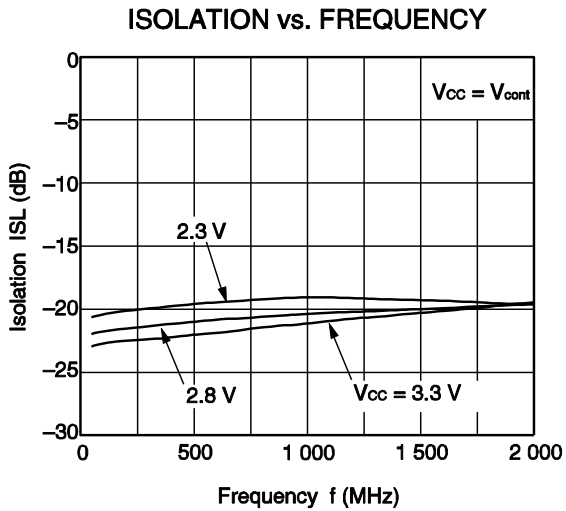
OUTPUT RETURN LOSS vs. FREQUENCY



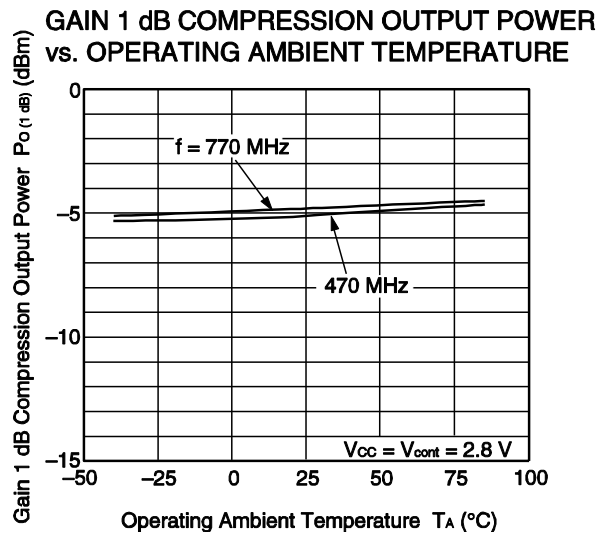
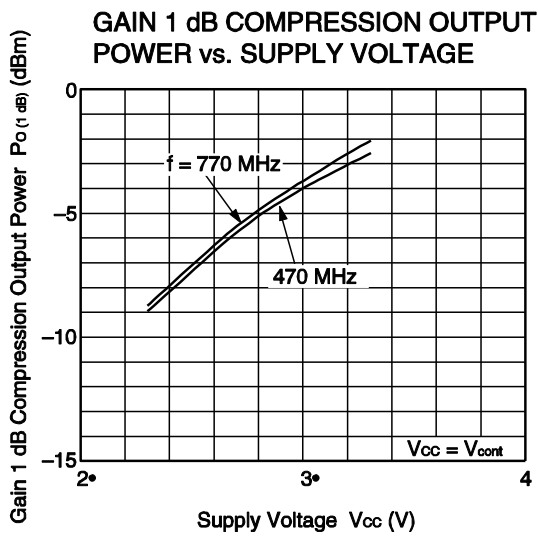
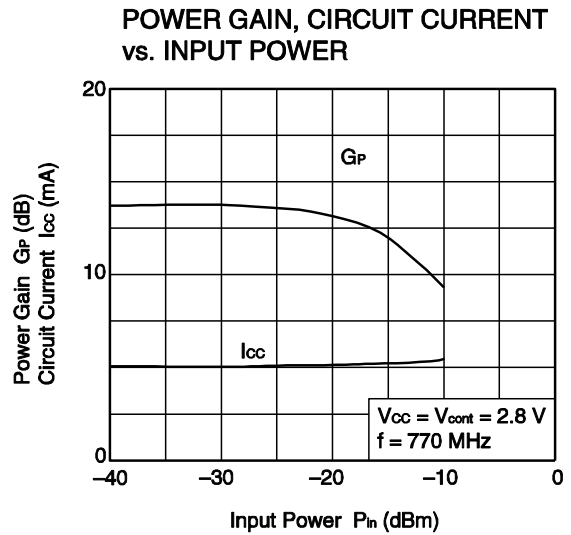
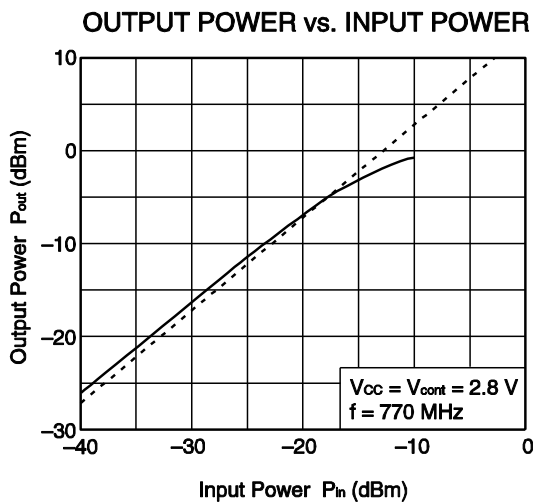
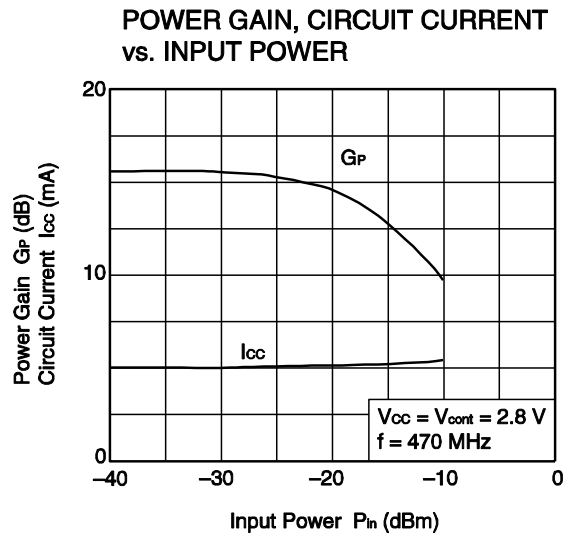
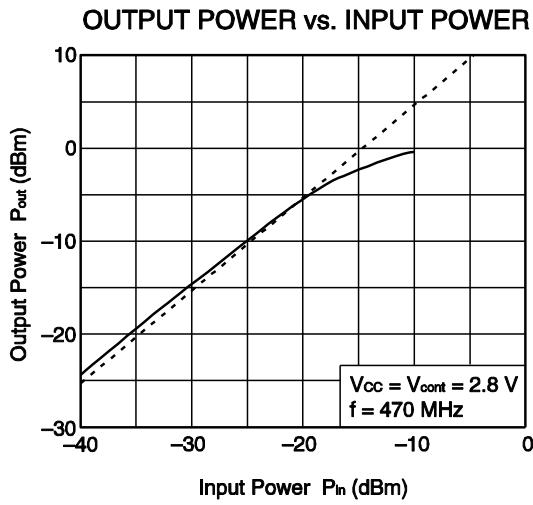
OUTPUT RETURN LOSS vs. FREQUENCY



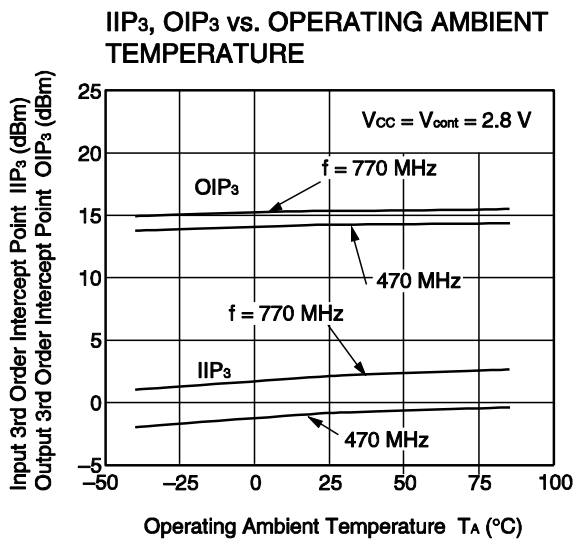
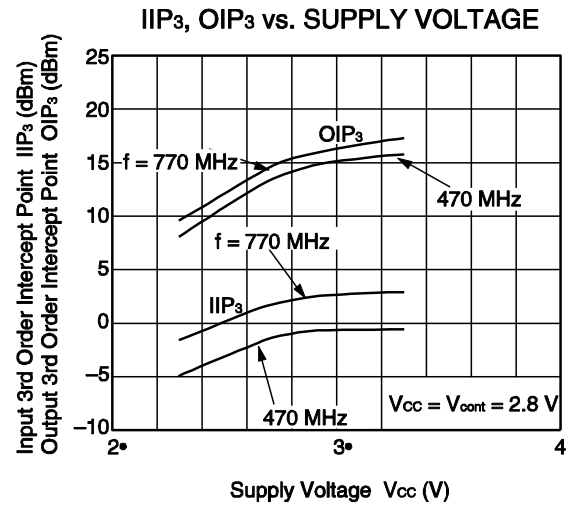
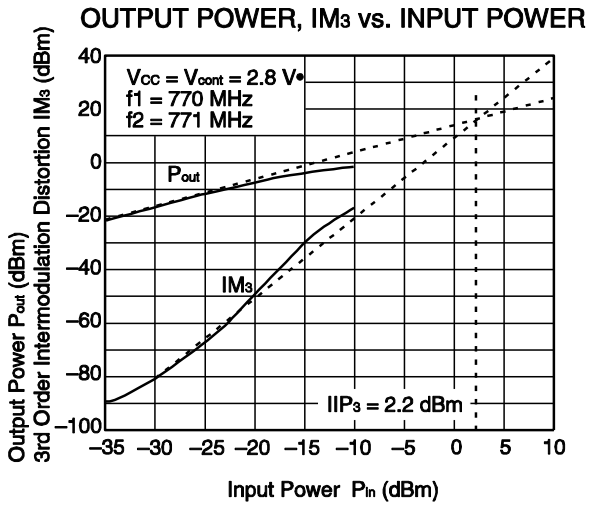
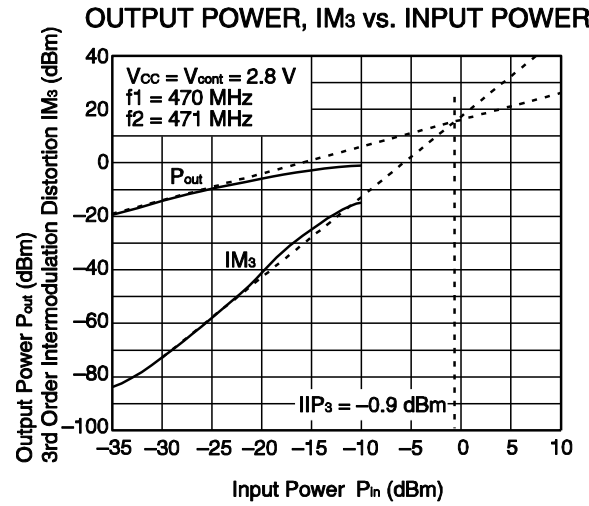
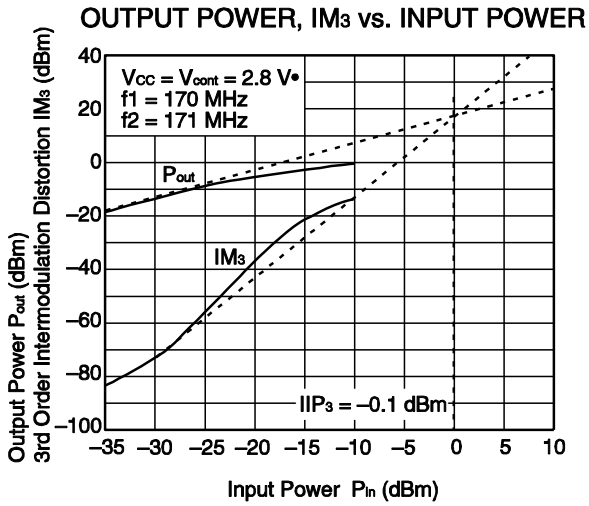
Remark The graphs indicate nominal characteristics.



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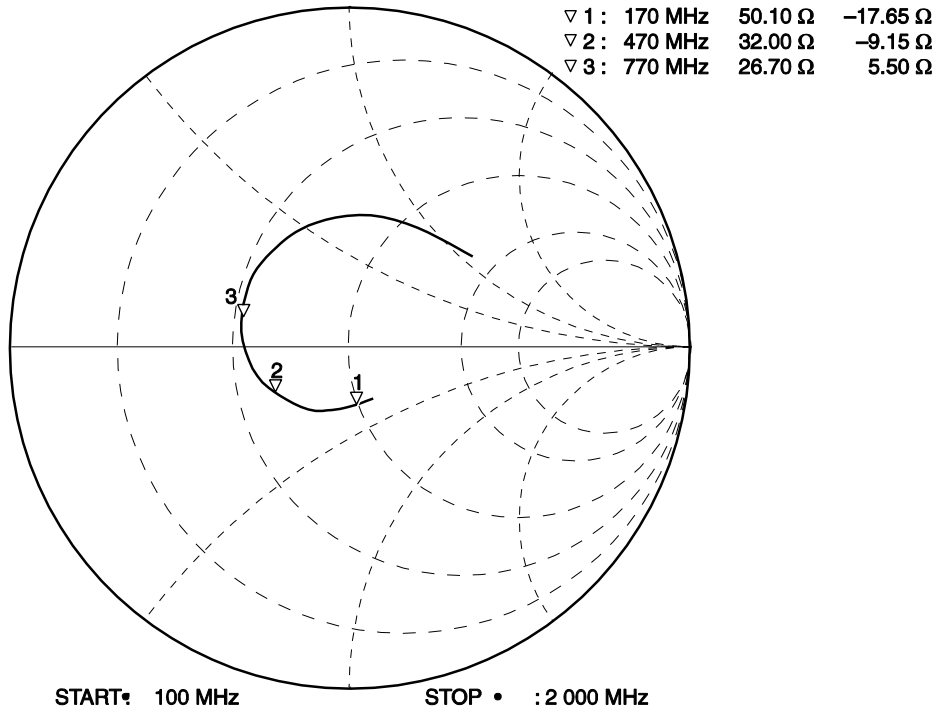
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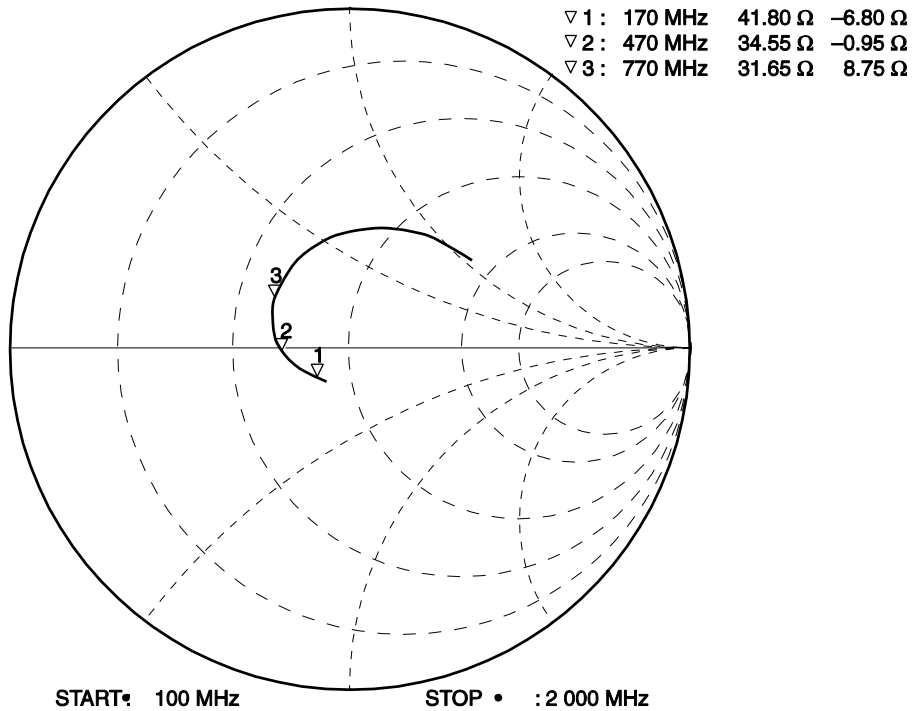
Remark The graphs indicate nominal characteristics.

S-PARAMETERS 1 (LNA-mode) ($T_A = +25^\circ\text{C}$, $V_{CC} = V_{cont} = 2.8\text{ V}$, monitored at connector on board)

S₁₁-FREQUENCY

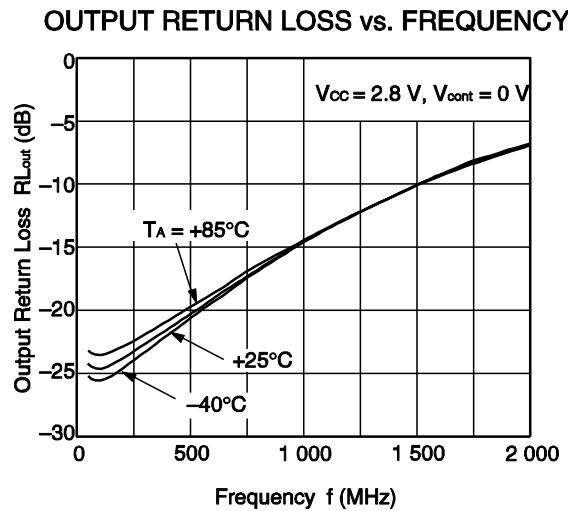
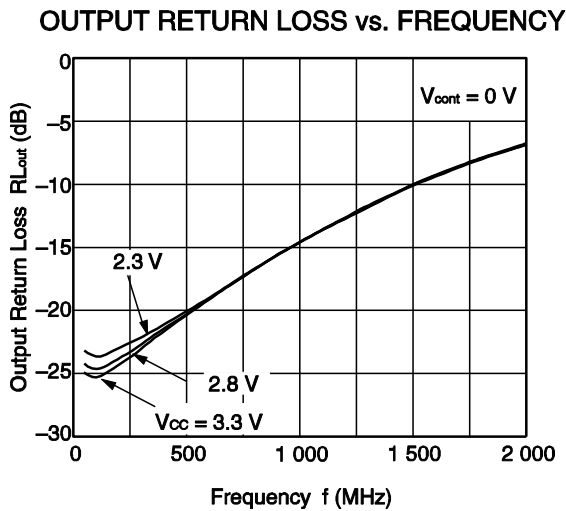
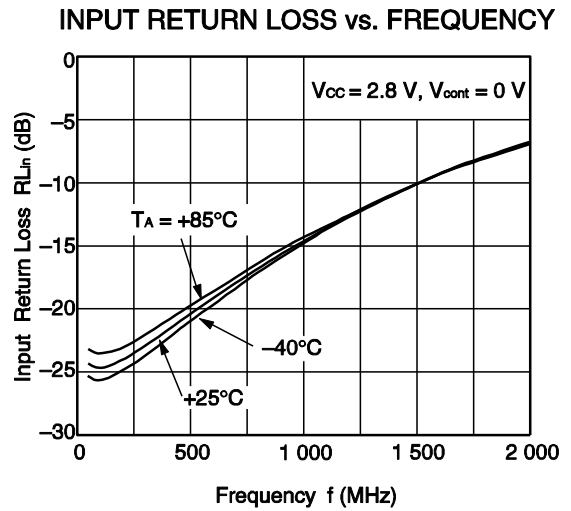
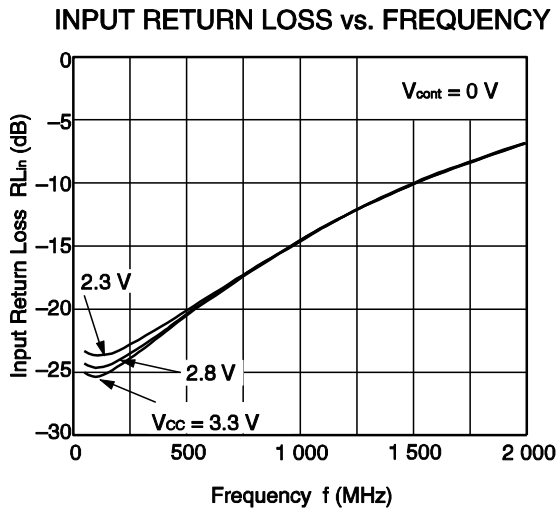
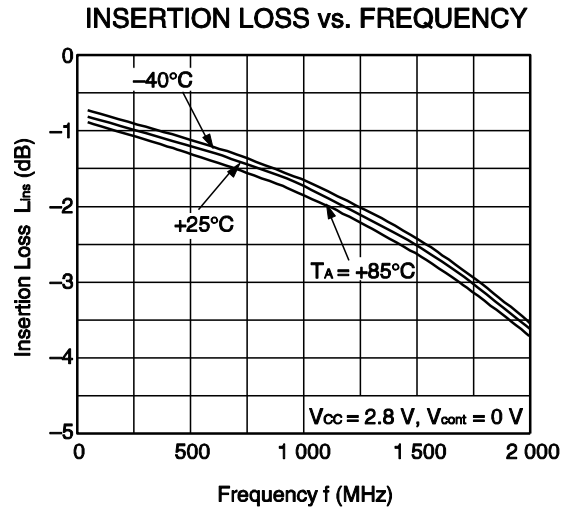
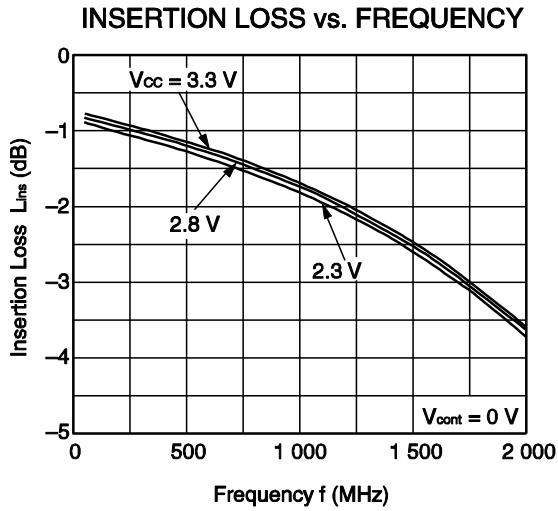


S₂₂-FREQUENCY



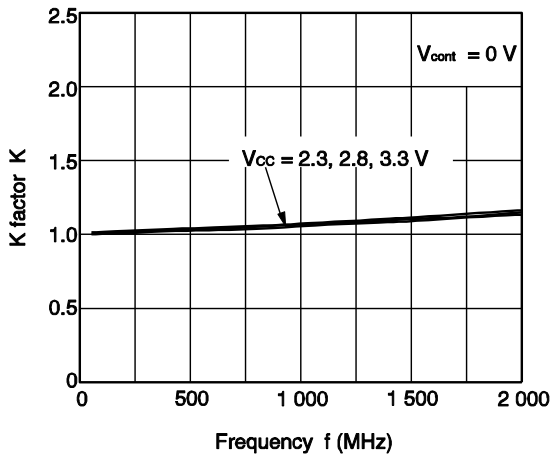
Remark The graphs indicate nominal characteristics.

TYPICAL CHARACTERISTICS 3 (Bypass-mode) ($T_A = +25^\circ\text{C}$, unless otherwise specified)

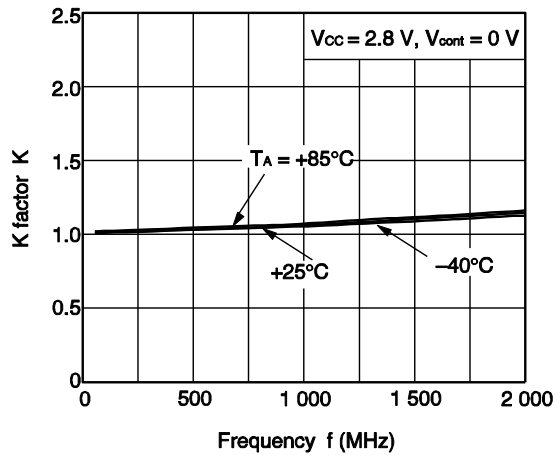


Remark The graphs indicate nominal characteristics.

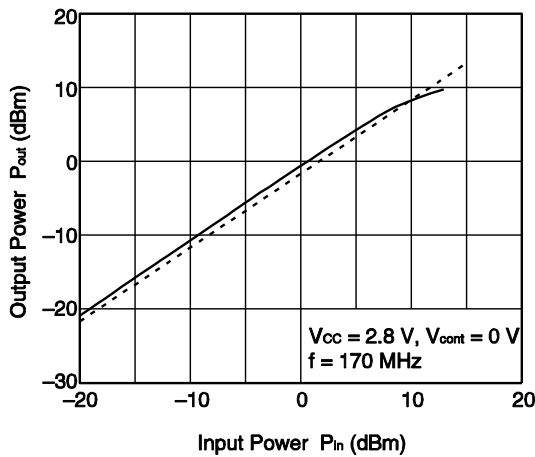
K FACTOR vs. FREQUENCY



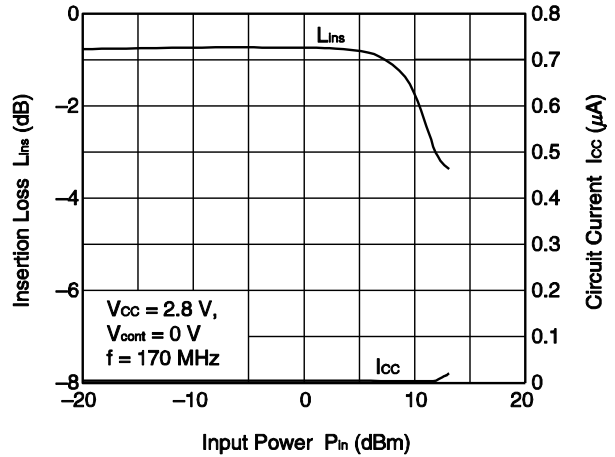
K FACTOR vs. FREQUENCY



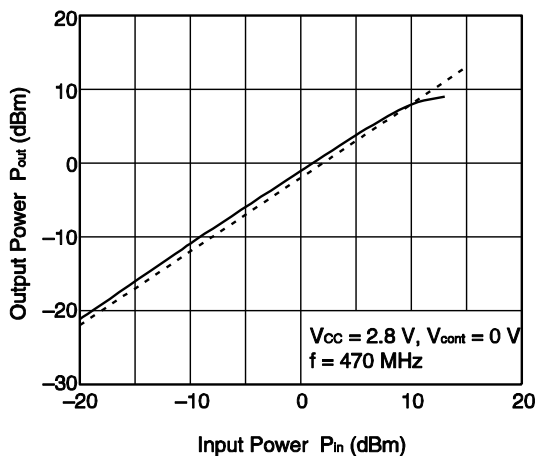
OUTPUT POWER vs. INPUT POWER



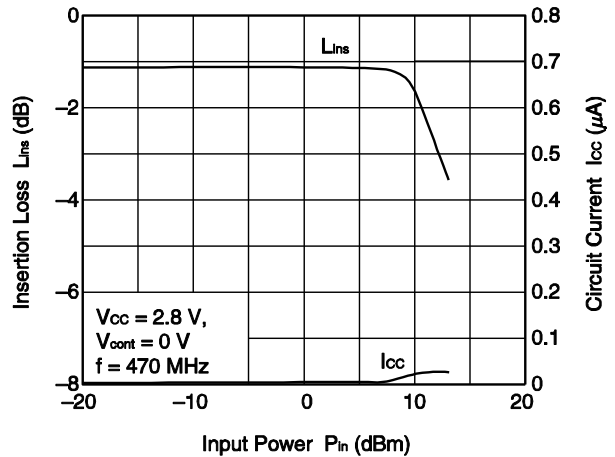
INSERTION LOSS, CIRCUIT CURRENT vs. INPUT POWER



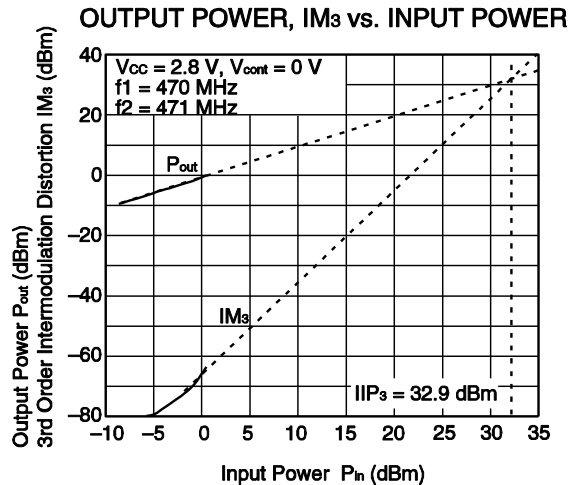
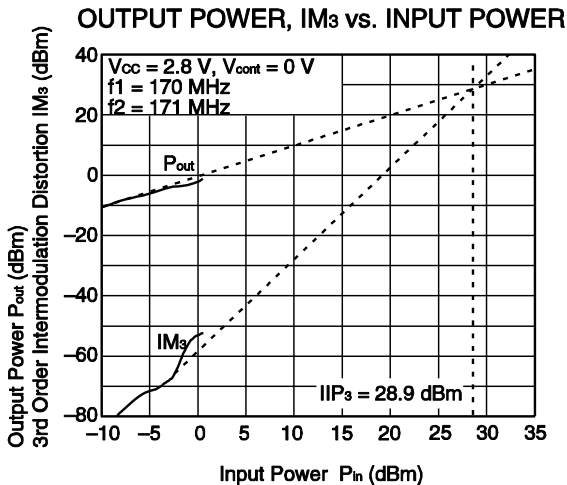
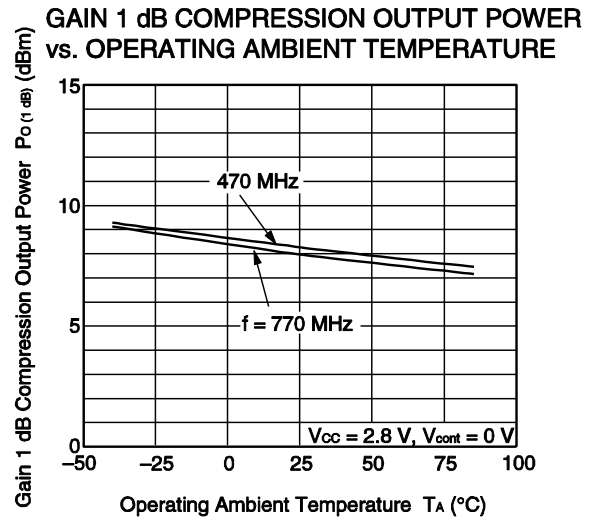
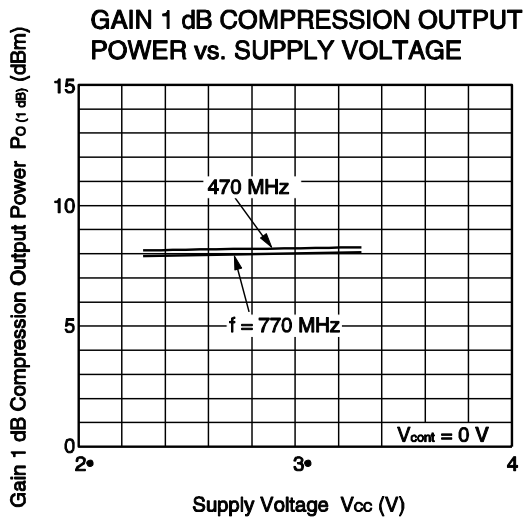
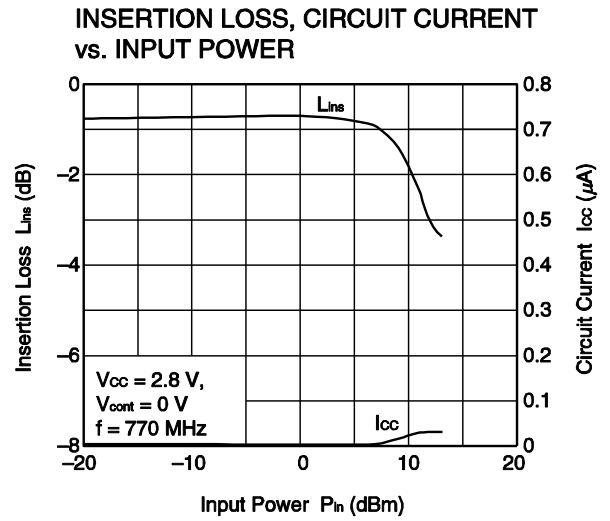
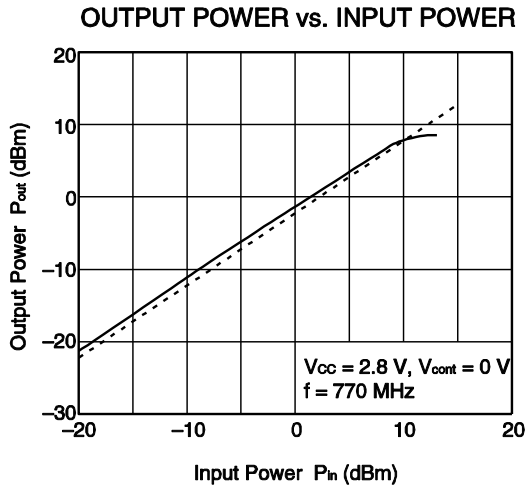
OUTPUT POWER vs. INPUT POWER



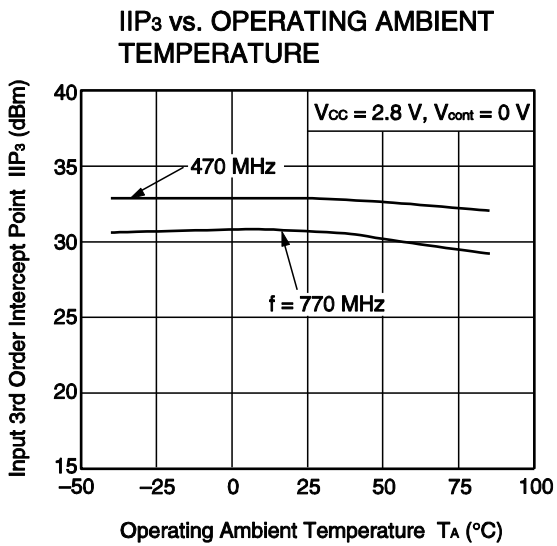
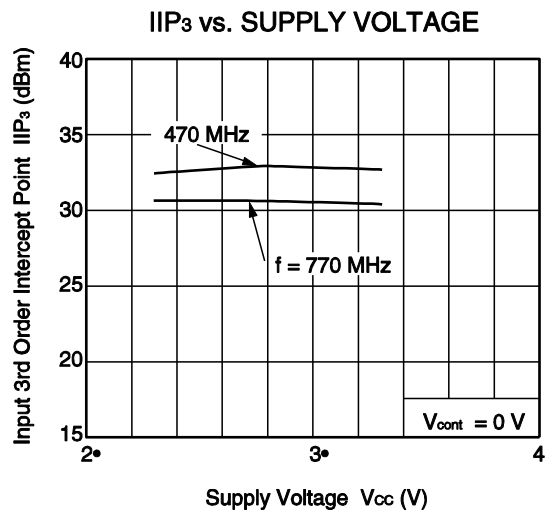
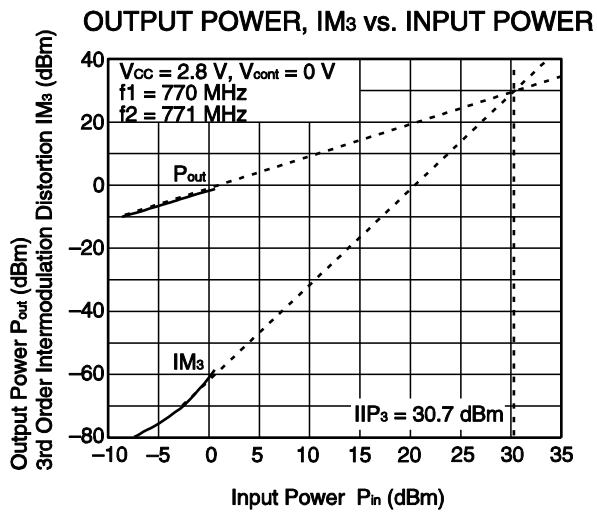
INSERTION LOSS, CIRCUIT CURRENT vs. INPUT POWER



Remark The graphs indicate nominal characteristics.



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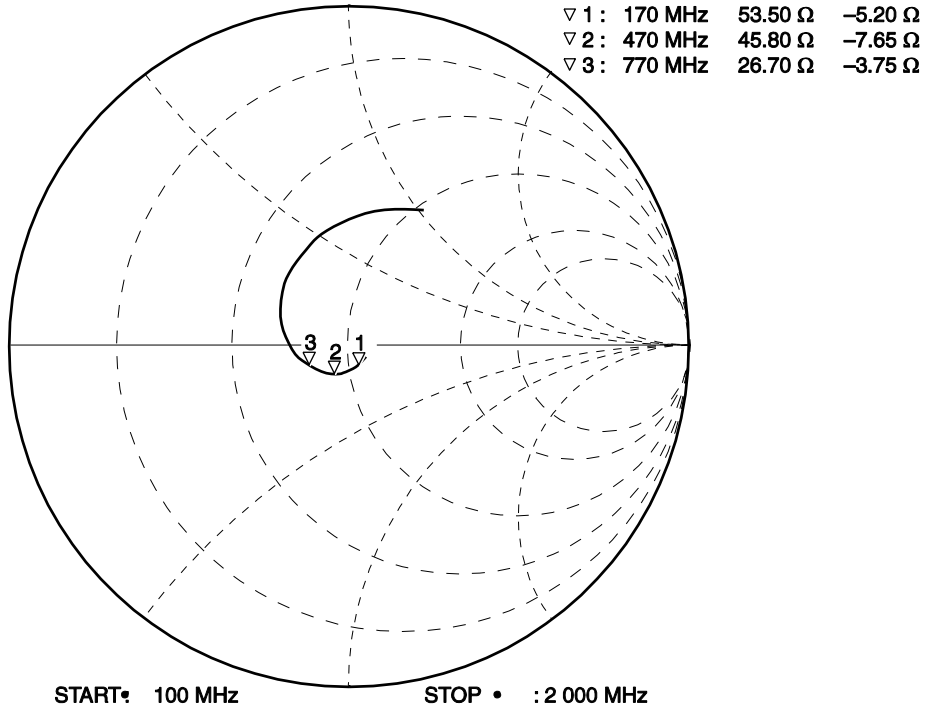


Remark The graphs indicate nominal characteristics.

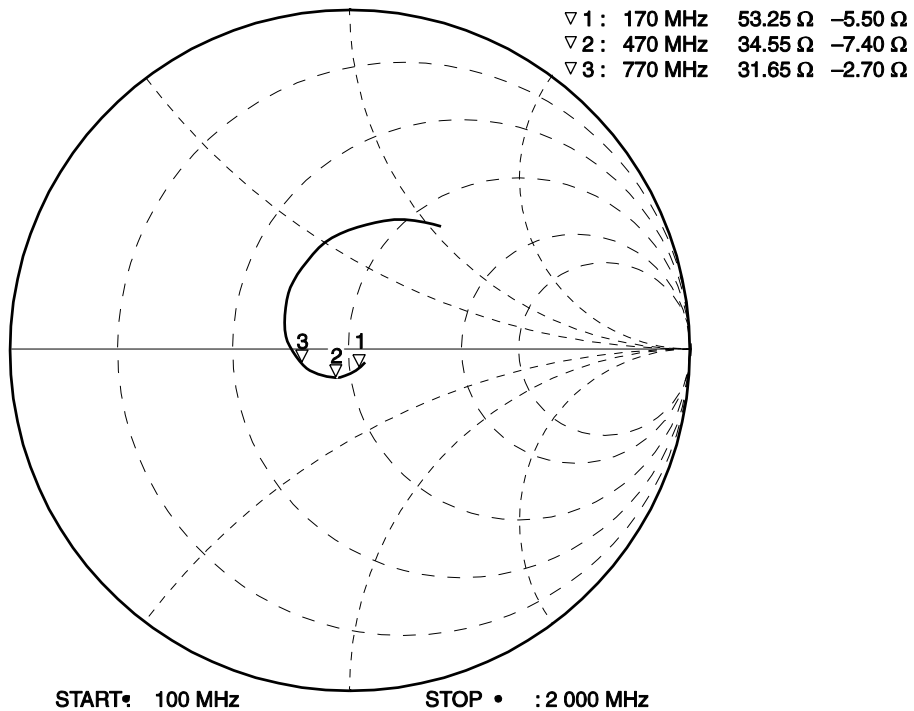
S-PARAMETERS 2 (Bypass-mode)

(T_A = +25°C, V_{CC} = 2.8 V, V_{cont} = 0 V, monitored at connector on board)

S₁₁-FREQUENCY



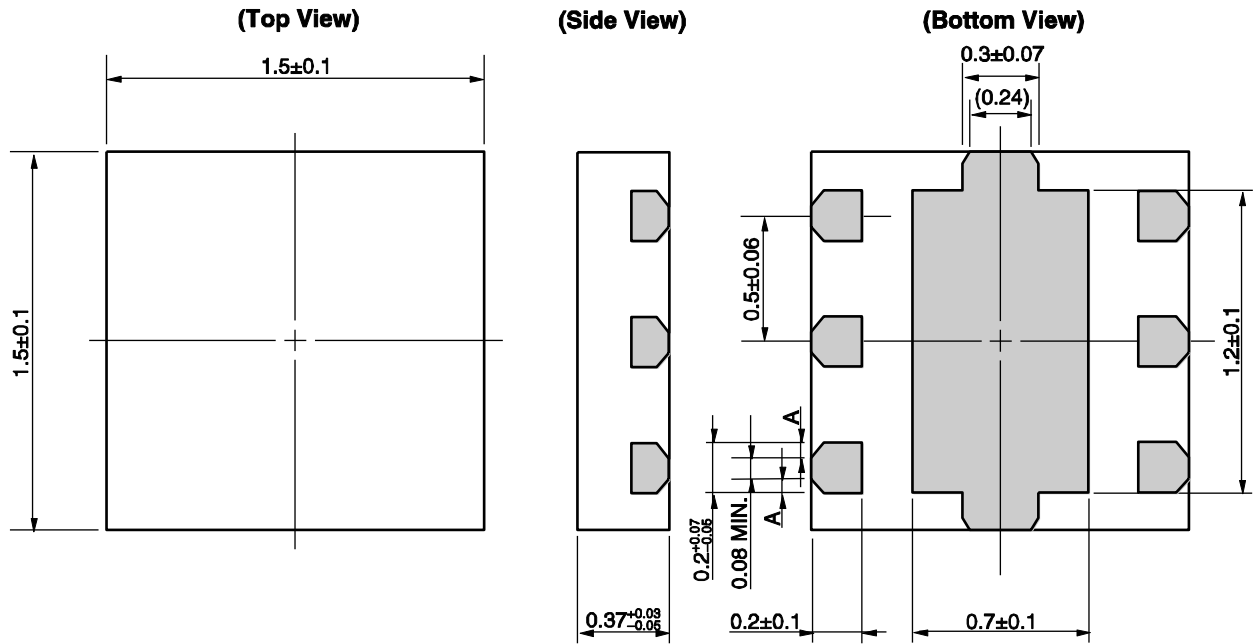
S₂₂-FREQUENCY



Remark The graphs indicate nominal characteristics.

PACKAGE DIMENSIONS

6-PIN PLASTIC TSON (T6N) (UNIT: mm)



Remark A>0

() : Reference value

NOTES ON CORRECT USE

- (1) Observe precautions for handling because of electro-static sensitive devices.
- (2) Form a ground pattern as widely as possible to minimize ground impedance (to prevent undesired oscillation).
All the ground terminals must be connected together with wide ground pattern to decrease impedance difference.
- (3) The bypass capacitor should be attached to Vcc line.
- (4) Do not supply DC voltage to INPUT pin.
- (5) Pin 5 (NC) should be connected to the ground pattern.

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature)	: 260°C or below
	Time at peak temperature	: 10 seconds or less
	Time at temperature of 220°C or higher	: 60 seconds or less
	Preheating time at 120 to 180°C	: 120±30 seconds
	Maximum number of reflow processes	: 3 times
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below
Partial Heating	Peak temperature (terminal temperature)	: 350°C or below
	Soldering time (per side of device)	: 3 seconds or less
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below

Caution Do not use different soldering methods together (except for partial heating).